1934272-1 ACTIVE

Z-PACK | Z-PACK TinMan

TE Internal #: 1934272-1

120 Position, Mating Alignment, Guide Slot Mating Alignment Type, 15 Row, 8 Column, PCB Mount Header, Z-PACK TinMan,

High Speed Backplane Connectors

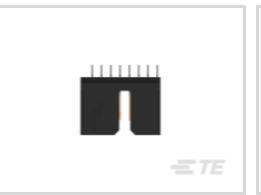
View on TE.com >



Connectors > PCB Connectors > Backplane Connectors > High Speed Backplane Connectors











Number of Positions: 120

Row-to-Row Spacing: 2.5 mm [.098 in]

Mating Alignment: With

Mating Alignment Type: Guide Slot

Number of Rows: 15

Features

Product Type Features

Backplane Module Type

Signal Arrangement	Differential	
Connector System	Board-to-Board	
Connector & Contact Terminates To	Printed Circuit Board	
PCB Connector Assembly Type	PCB Mount Header	
Shroud Style	Partially Shrouded	
Configuration Features		
Pairs per Column	5	
Number of Pairs	40	
Stackable	No	
Number of Signal Positions	80	
Backplane Architecture	Traditional Backplane	
Number of Positions	120	
Number of Rows	15	

Left



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Number of Differential Pairs per Column 5 Data Rate 10 Column 10 Column 5	Gb/s ack		
Data Rate 10 0 ody Features	nck		
dy Features	nck		
rimary Product Color Blac			
	nm[.236 in]		
ontact Features	nm[.236 in]		
Contact Mating Area Length 6 m	111[.200 111]		
'CB Contact Termination Area Plating Material Thickness .5 μ	um[20 µin]		
Contact Type Pin			
Contact Mating Area Plating Material Thickness .76	μm[29.92 μin]		
Contact Mating Area Plating Material Gol	old		
CB Contact Termination Area Plating Material Finish Mat	atte		
Contact Shape & Form Rec	ctangular		
CB Contact Termination Area Plating Material Tin			
Contact Base Material Pho	osphor Bronze		
Contact Current Rating (Max) .5 A	Δ		
rmination Features			
Termination Post & Tail Length 2.5	mm[.098 in]		
Termination Method to PCB	rough Hole - Press-Fit		
Mechanical Attachment			
Guide Hardware Wit	thout		
Mating Retention Wit	thout		
CB Mount Alignment Wit	thout		
CB Mount Retention Wit	th		
CB Mount Retention Type Act	tion/Compliant Tail		
Mating Alignment Wit			



Mating Alignment Type	Guide Slot			
Connector Mounting Type	Board Mount			
Housing Features				
Number of Shrouded Sides	2			
End Wall Location	Left			
Housing Material	LCP (Liquid Crystal Polymer)			
Centerline (Pitch)	1.9 mm[.075 in]			
Dimensions				
Connector Length	15.35 mm			
Connector Height	11.8 mm			
Connector Width	24.4 mm			
PCB Hole Diameter	.47 mm			
Row-to-Row Spacing	2.5 mm[.098 in]			
Usage Conditions				
Operating Temperature Range	-65 – 90 °C[-85 – 194 °F]			
Operation/Application				
Circuit Application	Signal			
Industry Standards				
Compatible With Agency/Standards Products	UL			
Compatible With Approved Standards Products	UL E28476			
UL Flammability Rating	UL 94V-0			
Packaging Features				
Packaging Method	Box & Tube, Tube			

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241)



Does	not	contain	REACH	SVHC
	1100	COITLAIL	$1 \times 1 \times$	\cup

Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Solder Process Capability

Not applicable for solder process capability

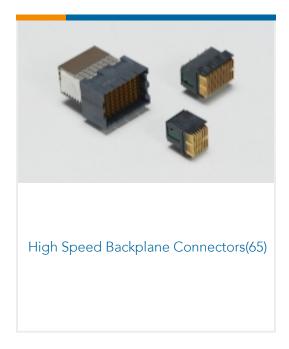
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Also in the Series | Z-PACK TinMan



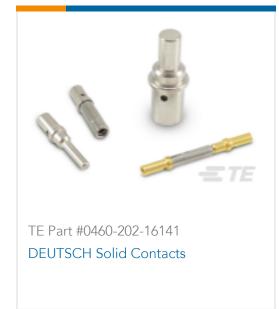
Customers Also Bought

















Documents

Product Drawings

Tin Man Header Assy 5x8 left

English

CAD Files

Customer View Model

ENG_CVM_1934272-1_B.3d_igs.zip

English

Customer View Model

ENG_CVM_1934272-1_B.3d_stp.zip

English

Customer View Model

ENG_CVM_1934272-1_B.2d_dxf.zip

English

3D PDF

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

High Speed Backplane Connectors catalog - Z-PACK TinMan High Speed, High Density Backplane Connector

English

Z-PACK TinMan High Speed High Density Backplane Connector Catalog 5-1773447-9

English

Product Specifications

Application Specification

English

120 Position, Mating Alignment, Guide Slot Mating Alignment Type, 15 Row, 8 Column, PCB Mount Header, Z-PACK TinMan, High Speed Backplane Connectors

